Drawing No: FMC-K-HTS-0001

CHIP FUSES; RECTANGULAR TYPE

FMC10, 16 Page:

1. Scope

1.1 This specification covers the detail requirements for chip fuses; rectangular type, style of FMC10, 16.

1.2 Applicable documents

UL248-1-2000 Low-Voltage Fuses-Part1: General Requirements

UL248-14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

CSA C22.2 No.248.1–2000 Low-Voltage Fuses-Part1: General Requirements

CSA C22.2 No.248.14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

2. Classification

Type designation shall be the following form.

1 Chip fuses; rectangular type

2 Size



3 Rated current

4 Optional code

Symbol	Optional code		
AB			
WB	Standard		
WH			

5 Packaging form

99	
В	Bulk (loose package)
TH	Donor toning
TP	Paper taping

3. Safety standard approval

- UL248-1 and UL248-14
- CSA C22.2, No. 248.1-00 and CSA C22.2, No. 248.14-00

The file number to be designated by UL and C-UL shall be as follows: E176847



FMC10, 16 Page: 2/9

Drawing No:

FMC-K-HTS-0001

4. Rating

The ratings shall be in accordance with Table-1.

4.1 Optional code: AB

Table-1(1)

Style	Rated current		Internal resistance value	Rated	Breaking	Time / current characteristic		
	Symbol	(A)	Marking symbol	(m Ω max.)	voltage (V)	capacity (A)	Current	Pre-arcing time
	501	0.5	F	240				
	751	0.75	Α	140				
	102	1.0	L	95	DC24	224 35	100% 200% 300%	4 h min. 5 s max. 0.2 s max.
FMC10	132	1.25	М	73				
1 IVIC 10	152	1.5	Η	60	DC24			
	202	2.0	S	41				
	252	2.5	T	32				
	302	3.0	R	25				

4.2 Optional code: WB

Table-1(2)

Style	Rated current		Internal resistance value	Rated	Breaking	Time / current characteristic		
	Symbol	(A)	Marking symbol	(m Ω max.)	voltage (V)	capacity (A)	Current	Pre-arcing time
	501	0.5	F	260				
	751	0.75	Α	140				
	102	1.0	L	110				
	132	1.25	M	80	DC32 35	25	100%	4 h min. 5 s max. 0.2 s max.
FMC16	152	1.5	Η	65				
FIVIC 10	202	2.0	S	45		33	200% 300%	
	252	2.5	Т	32			30076 0.2	0.2 3 max.
	302	3.0	R	26				
	402	4.0	Χ	18				
	502	5.0	Υ	14				

Drawing No: FMC-K-HTS-0001

CHIP FUSES; RECTANGULAR TYPE

FMC10, 16 Page: 3/9

4.3 Optional code: WH

Table-1(3)

	F	Rated curre	ent	Internal resistance value	Rated	Breaking	Time / current characteristic	
Style	Symbol	(A)	Marking symbol	(mΩ max.)	voltage (V)	capacity (A)	Current	Pre-arcing time
	501	0.5	<u>F</u>	250				
	751	0.75	<u>A</u>	150				
	102	1.0	<u>L</u>	100				
	132	1.25	M	70				
	152	1.5	<u>H</u>	60			100%	4 h min.
FMC10	202	2.0	<u>S</u>	40	DC24	35	200%	5 s max.
	252	2.5	Τ	30			300%	0.2 s max.
	302	3.0	<u>R</u>	25				
	322	3.15	J	24				
	402	4.0	<u>X</u>	18				
	502	5.0	<u>Y</u>	14				
	501	0.5	OF	400				4 h min.
	631	0.63	OI	300				
	751	0.75	OA	210				
	801	8.0	OK	180				
	102	1.0	OL	115				
	132	1.25	OM	90			100%	
FMC16	152	1.5	OH	70	DC32	35	200%	5 s max.
1 101010	162	1.6	ON	60	D002	00	300%	0.2 s max.
	202	2.0	OS	50			00070	oiz o maxi
	252	2.5	OT	37				
	302	3.0	OR	28				
	322	3.15	OU	26				
	402	4.0	OX	18				
	502	5.0	OY	14				

4.4 Working temperature range: -55 to +125(°C)

5. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol			Packaging form Standard packaging quantity / units		Standard packaging quantity / units	Application
В	Bulk (loose package)		1,000 pcs.	FMC10, 16		
TH	Paper taping 8mm width, 2mm pitches		10,000 pcs.	FMC10		
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	FMC16		

Drawing No: FMC-K-HTS-0001

CHIP FUSES; RECTANGULAR TYPE

FMC10, 16 Page: 4/9

6. Dimensions

6.1 The resistor shall be of the design and physical dimensions in accordance with Figure-1 and Table-3.

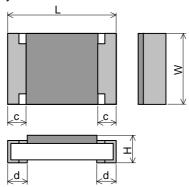


Figure-1

Table-3 Unit: mm

Style	Optional code	L	W	Н	С	d
EMC10	WH	1 0 1 0 0 5	0.510.05	0.35±0.05	0.210.40	0.05+0.10
FMC10	AB	1.0±0.05	0.5±0.05	0.38±0.05	0.2±0.10	0.25±0.10
FMC16	WB,WH	1.6±0.1	0.8 +0.15 -0.05	0.45±0.10	0.3±0.15	0.3±0.1

6.2 Net weight (Reference)

Style	Net weight(mg)
FMC10	0.6
FMC16	2

7. Marking

The Marking symbol of Sub-clause 4.1 shall be marked on over coat side.

(Example)

Style	Optional code	Marking symbol	Content
FMC10	AB	S	FMC10 202 AB
FMC10	WH	<u>s</u>	FMC10 202 WH
FMC16	WB	S	FMC16 202 WB
FMC16	WH	OS	FMC16 202 WH

KAMAYA OHM

Drawing No: FMC-K-HTS-0001 CHIP FUSES; RECTANGULAR TYPE

FMC10, 16 Page: 5/9

8. Performance

8.1 Unless otherwise specified, the standard range of atmospheric conditions for tests is as follows;

Ambient temperature: 5 °C to 35 °C, Relative humidity: 45 % to 85 %, Air presser: 86 kPa to 106 kPa

If there is any doubt the results, measurements shall be made within the following:

Ambient temperature: 20 °C \pm 2 °C, Relative humidity: 60 % to 70 %, Air presser: 86 kPa to 106 kPa

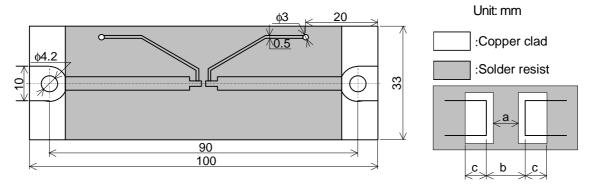
8.2 The performance shall be satisfied in Table-4.

Table-4(1)

No	Toot itoms	Condition of test	Dorford	manaa raguiramanta
No.	Test items		Performance requirements	
1	Temperature rise	The fuse shall be mounted on the test substrate as shown in Figure–2. Measurement temp.: 10 °C to 30 °C Test current: Rated current The temperature at the hottest point on the surface of the fuse shall be measured after temperature equilibrium has been attained.	75 °C max.	
2	Time / current characteristic	The fuse shall be mounted on the test substrate as	Current	Pre-arcing time
		shown in Figure–2. Test current shall be applied for continuously.	100% 200% 300%	4 h min. 5 s. max. 0.2 s max.
3	Terminal bond strength of	JIS C 60068-2-21 Ue1	Change of	internal resistance:
	the face plating	The fuse shall be mounted on the test substrate as shown in Figure–2. Bending value: 3 mm(Among the fulcrums: 90 mm) Duration: $10 \text{ s} \pm 1 \text{ s}$	±10% No evidence of mechani damage.	
4	Resistance to soldering heat	Test by a piece. Temp. of solder bath: 260 °C ± 5 °C Immersion time: 10 s ± 1 s After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance. • Reflow soldering Pre–heating: 150 °C ~ 180 °C, 120 s max. Peak: 260 °C ± 5 °C, 10 s max. Reflow cycle: 2 times After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance.	Change of internal resistance: ±10% No evidence of appearance damage	
5	Solderability	JIS C 60068-2-58 Test by a piece Flux: Rosin–Methanol Temp. of solder: bath: 235 °C ± 5 °C Immersion time: 2 s ± 0.5 s	The surface of terminal immerse shall be min. of 95 % covered win a new coating of solder.	
6	Rapid change temperature	JIS C 60068-2-14 Na The fuse shall be mounted on the test substrate as shown in Figure–2. Lower temperature: –55 °C Upper temperature: +125 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles	Change of ±10% No evide damage	internal resistance: ence of appearance

FMC10, 16 Page: 6/9

9. Test substrate



Style	а	b	С
FMC10	0.3	0.6	0.65
FMC16	0.6	1.0	0.5

Figure-2 FMC TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass

Thickness: 1. 6mm Thickness of copper clad: 0. 035mm

10. Taping

10.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010

10.2 Taping dimensions

10.2.1 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.

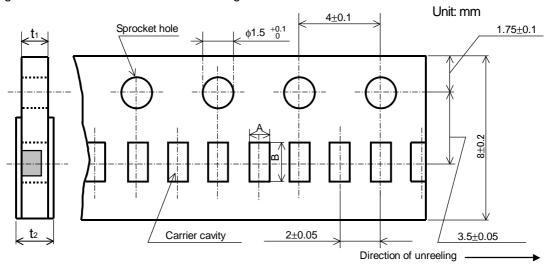


Figure-3

	Unit: mm			
Style	Α	В	t 1	t ₂
FMC10	0.65 +0.05	1.15 ^{+0.05} _{-0.10}	0.4 ± 0.05	0.5max.

Drawing No:

Title: CHIP FUSES; RECTANGULAR TYPE

FMC10, 16 Page: 7/9

10.2.2 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-4 and Table-6.

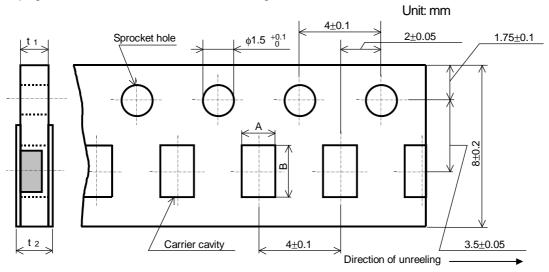


Figure-4
Table-6 Unit: mm

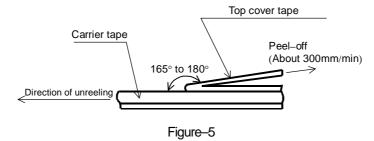
Style A B t₁ t₂

FMC16 1.15±0.15 1.9±0.2 0.6±0.1 0.8 max.

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure–5.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

The maximum number of missing components shall be one or 0.1%, whichever is greater.

8). The fuses shall be faced to upward at the over coating side in the carrier cavity.



FMC10, 16 Page: 8/9

10.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-6 and Table-7.

Plastic reel (Based on EIAJ ET-7200C)

Unit: mm

A
B
Figure-6
Table-7

Unit: mm

Note

	Table_7		Unit: mm
Style	Α	В	Note
FMC10, 16	9 +1.0	11.4±1.0	Injection molding
		13±1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

10.4 Leader and trailer tape.

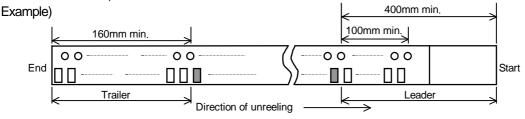


Figure-7

11. Marking on package

The label of a minimum package shall be legibly marked with follows.

11.1 Marking A

- (1) Classification (Style, Rated current, Optional code, Packaging form) (2) Quantity (3) Lot number
- (4) Manufacturer's name or trade mark (5) UL and /or C–UL recognized component mark (6) Others 11.2 Marking B (KAMAYA Control label)

FMC10, 16 Page: 9/9

12. Recommended Derating for Rated Current

This fuse will recommend use by the current reduction value according to the following derating curve.

Nominal Derating

Nominal Derating ≤ 75% of Rated Current

*FMC10 Optional code: WH, Rated current ≥ 3.15A: Nominal Derating ≤ 70% of Rated Current

Temperature Derating

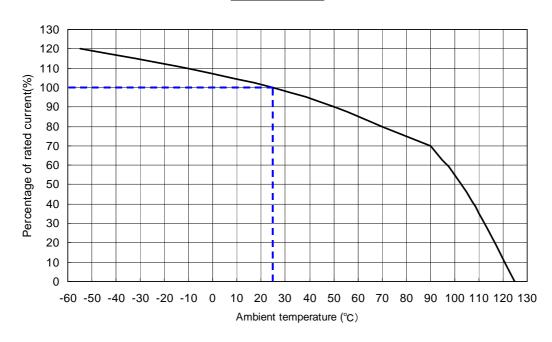
Please refer to the following graph regarding the current derating value for ambient temperature.

Ex.) If FMC16 202WH (Rated Current 2.0A) is used under ambient temperature 70°C,

Kamaya recommends, less than the current value derated as below,

Rated Current: $2.0A \times (Nominal Derating: 75\% \times Temperature Derating: 80\%) = 1.2A$

Derating curve



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<u>FMC16-132-AH FMC10132ABTH FMC16501ABTP FMC10202ABTH FMC16102ABTP FMC16202ABTP</u>
FMC10501ABTH FMC10302ABTH FMC10102ABTH FMC16152ABTP FMC10252ABTH